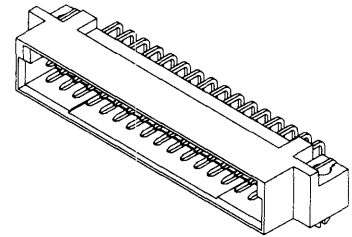


molex® 2.54mm (.100") Pitch
DIN 41612
Header

53294/53319
Right Angle



FEATURES AND SPECIFICATIONS

Features and Benefits

- Sizes 16 to 64 circuits
- Face mount for wave soldering applications
- DIN 41612 and IEC 603-2 compatible
- Two points of contact provide low insertion force and reliable connection

Reference Information

Product Specification: PS-53294/PS-53319
Packaging: Tray
UL File No.: E29179 (for 53294 only)
CSA File No.: LR19980
Mates With: 52299, 52479 and 52482
Designed In: Millimeters

Electrical

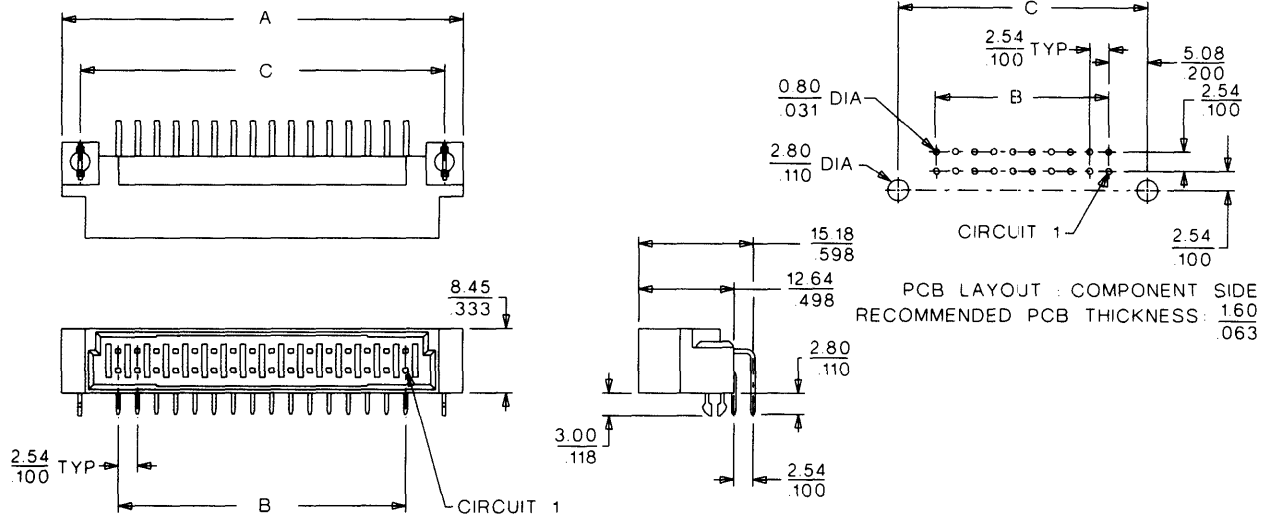
Voltage: 300V
Current: 2.0A
Contact Resistance: 20mΩ max.
Dielectric Withstanding Voltage: 1000V AC
Insulation Resistance: 10⁴ MΩ min.

Physical

Housing: Glass-filled PBT, UL 94V-0
Contact: Brass
Metal Peg: Phosphor Bronze
Plating: See Table
Operating Temperature: -55 to +105°C

Backplane Connector Systems

CATALOG DRAWING (FOR REFERENCE ONLY)



ORDERING INFORMATION AND DIMENSIONS

Circuits	Order No.		Dimension		
	Without Metal Peg	With Metal Peg	A	B	C
10		53319-0100	25.22 (.993)	10.16 (.400)	20.32 (.800)
16	53294-016X	53319-016X	32.84 (1.300)	17.78 (.700)	27.94 (1.096)
20	53294-020X	53319-020X	37.92 (1.493)	22.86 (.900)	33.02 (1.300)
32	53294-032X	53319-032X	53.16 (2.093)	38.10 (1.500)	48.26 (1.900)
44	53294-044X	53319-044X	68.40 (2.693)	53.34 (2.100)	63.50 (2.500)
50	53294-050X	53319-050X	76.02 (2.993)	60.96 (2.400)	71.12 (2.800)
64	53294-064X	53319-064X	93.80 (3.693)	78.74 (3.100)	88.90 (3.500)

Replace X with plating no., 0-3

Plating No. 0: 0.1µm Gold with Nickel underplate overall and Tin/Lead in solder area
Plating No. 1: 0.3µm Gold with Nickel underplate overall and Tin/Lead in solder area
Plating No. 2: 0.5µm Gold with Nickel underplate overall and Tin/Lead in solder area
Plating No. 3: 0.76µm Gold with Nickel underplate overall and Tin/Lead in solder area